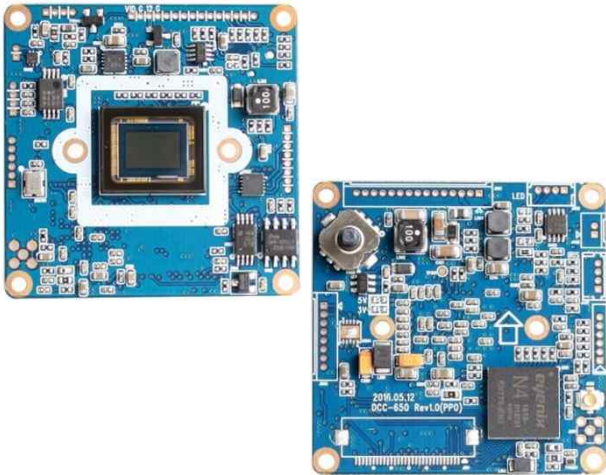


# DCC-650

## CMOS VIDEO MODULE



### Main Features

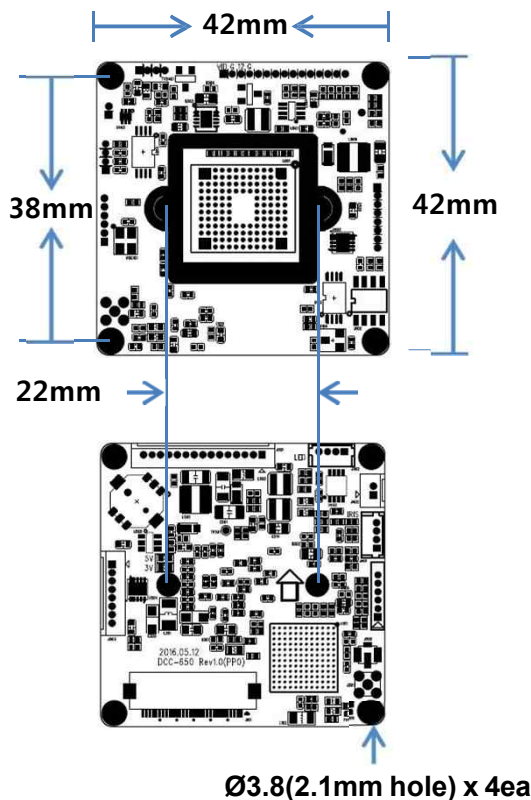
- 1/1.9" 2.12M(1080P) Sony CMOS Image Sensor
- 2Mega Pixels (1080P25/30/50/60, 720P25/30/50/60)
- Mountable Lens: Fixed, Auto VF, Auto ICR VF Lens, AF VF Lens
- TDN ICR Mechanism Available
- WDR / 3D-NR / DSS(Sens-up) Supported
- OSD Available
- HD-SDI Video Out Supporting standard SMPTE protocol
- EX-SDI Video Out Supported
- Analog Composite Video Out
- CMOS HD-SDI Video Module (42x42 1-board)



### Specifications

Model	DCC-650
Signal System	HD-SDI (Serial Data Interface) or EX-SDI
Pickup Device	1/1.9"(D-8.58mm) 2.12M SONY CMOS Sensor
Scanning System	Progressive Scan (16:9)
Sync. System	Internal
Total Pixels	2.42M [1952(H)x1241(V)]
Effective Pixels	2.12M [1937(H)x1097(V)]
Scanning Frequency	30Hz(VD) for NTSCout   25Hz(VD) for PAL out
Min. Illumination	0.02Lux(F2.5 – 30IRE), 0.01(ICR on) 0.0006Lux(DSS on)
Mechanical ICR	Available (Option)
H-Resolution	More than 1,000TV Lines(H)
S/N Ratio	More than 50dB (AGCoff)
Video Out 1	HD-SDI or EX-SDI: 1080p@25/30/50/60, 720p@25/30/50/60
Video Out 2	Composite Video 1V p.p (NTSC/PAL - 75Ω)
Lens	DC Auto & Fixed Iris Lens
Lens (Mount)	Board (M12) and VF (Ø14) – Lens Holder
OSD	Option: Built-in OSD Switch or OSD Board
Camera Title	Off, On(Max. 8 Characters)
Language	English, Chinese(Simplified), Chinese(Traditional), Japanese, Korean
Exposure	DC, Manual
White Balance	AWB, ATW, Push Lock, Manual
BLC	Off, HLC, BLC, WDR * WDR is not operated when manual shutter mode or CVBS output mode is selected.
Day & Night Mode	AUTO, COLOR, B/W, EXT
Gain Control	AGC (0~10)
Electronic Shutter	1/25(30)~1/30,000sec
Noise Reduction	3DNR (Off, Low, Middle, High)
DSS(Sens-up)	X32
Mirror	Off, On(Mirror, Flip)
Other Features	Motion Detection (4 Zones), Privacy Mask (16 Zones), Flickerless, Lens Shading, Gamma, D-zoom, Defog etc.
Protocol	Pelco-D and Parantek Serial Protocol Supported
Power Source	DC12V
Power Consumption	Less than 2.2 Watts (180mA)
Operating Temp.	-10℃ ~ 55℃ (Humidity :0%RH ~ 90%RH)
Size (mm)	42(W) x 42(D) – 1 board
Weight	10 g (Including OLPF)

### Dimension



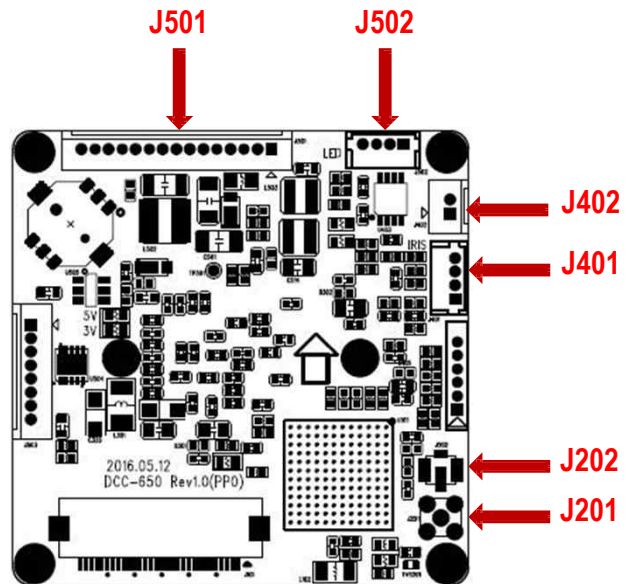
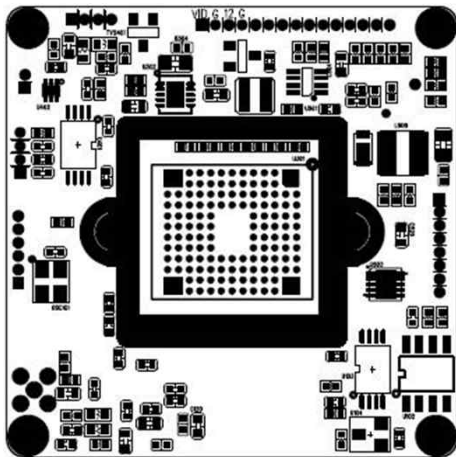
### Option

- Mechanical TDN ICR
- Lens

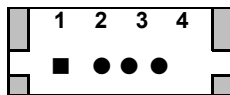
# DCC-650

## CMOS VIDEO MODULE

### Pin Connections



### J401 – DC IRIS



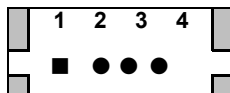
No.	Pin Item	No.	Pin Item
1	DMP+	3	DRV+
2	DMP-	4	GND

Wafer DIP type: **1.25mm pitch – 4pin**

Manufacturer: **Molex**

MFG Part Number: **53047-0410**

### J502 – IR LED Board



No.	Pin Item	No.	Pin Item
1	DC12V	3	EXT_DN (CDS)
2	GND	4	D&N OUT

Wafer DIP type: **1.25mm pitch – 4pin**

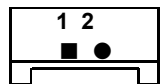
Manufacturer: **Molex**

MFG Part Number: **53047-0410**

### J201 – HD-SDI Out - MMCX

### J202 – HD-SDI Out - MHF

### J402 – TDN ICR



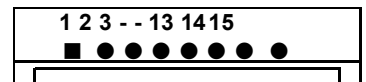
No.	Pin Item	No.	Pin Item
1	ICR (+)	2	ICR (-)

Wafer DIP type: **1.25mm pitch – 2 pin**

Manufacturer: **Yeonho**

MFG Part Number: **12512WS-02B**

### J501 – Multi Ports



No.	Pin Item	No.	Pin Item
1	CVBS	9	OSD Key (Left)
2	GND	10	EXT DN (B/W:High 3.3V)
3	DC12V	11	D&N Out (B/W:High 3.3V)
4	GND	12	RS485 TTL 3.3V TXD
5	OSD Key (Down)	13	RS485 TTL 3.3V RXD
6	OSD Key (Up)	14	RS485 TTL 3.3V CTL
7	OSD Key (Set)	15	DC 3.3V
8	OSD Key (Right)		

Wafer DIP type: **1.25mm pitch – 15pin**

Manufacturer: **Yeonho**

MFG Part Number: **12512WS-15B**